

MATERIALS AND FINISHES:

BODY ZINC ALLOY
SEE TABLE

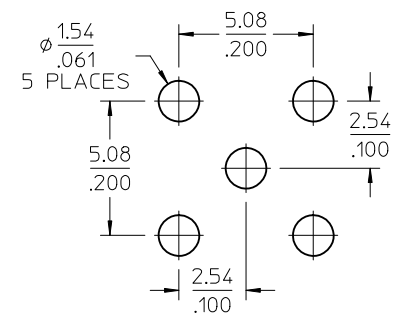
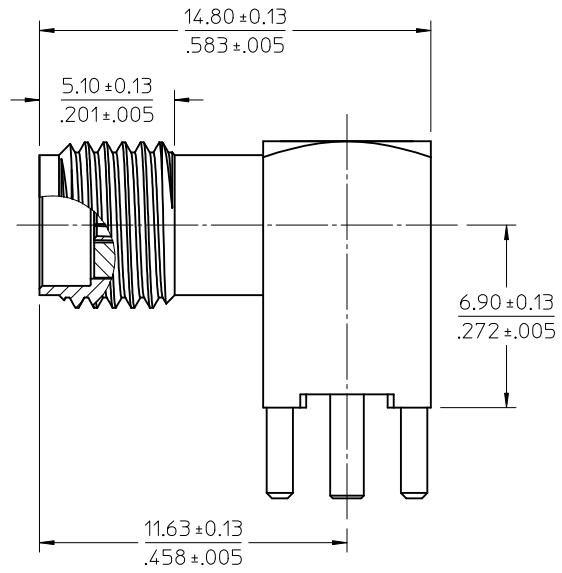
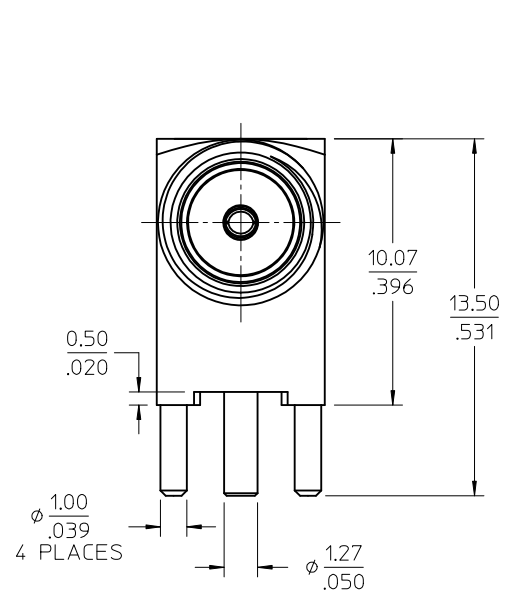
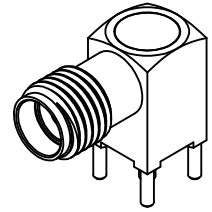
INSULATOR TEFLON

CONTACT (MATING END) BERYLLIUM COPPER
PLATED GOLD

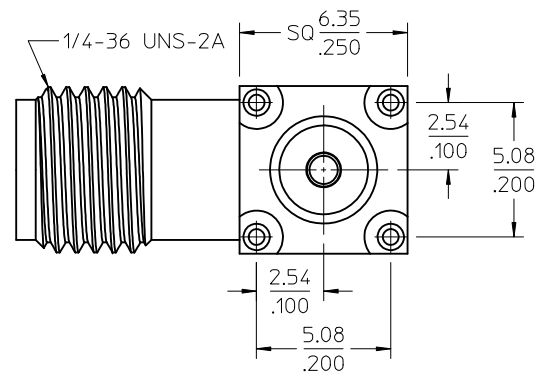
CONTACT (PCB END) BRASS
PLATED GOLD

COVER BRASS
SEE TABLE

PACKAGING SEE TABLE



RECOMMENDED PCB CONFIGURATION



73391-0083	BODY, PIN, AND COVER PLATED GOLD 1u" MIN	73391-0083 TRAY (80 CAV.)
73391-0082	BODY, AND COVER PLATED NICKEL	73391-0080 TRAY (20 CAV.)
73391-0081	BODY, PIN, AND COVER PLATED GOLD 10u" MIN	73391-0081 TRAY (80 CAV.)
73391-0080	BODY, AND COVER PLATED NICKEL	73391-0080 TRAY (80 CAV.)
PART NO.	DESCRIPTION	PACHAGING

PS-73598-0111	SPECIFICATION
MIL-STD-348A, FIG. 310.1	INTERFACE
SPECIFICATION	DESCRIPTION

CHG: REDRAW AND MEASUREMENT PER RFI2-E034 EC NO: URF2012-0310 DRW:RYEH 2011/12/02 CHKD: APPR:HUANG 2011/12/13 A5	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± --- ANGULAR ± 2 °	DIMENSION STYLE MM/IN DRAWN BY: LYNN LIN DATE: 1998/12/08 CHECKED BY: A. CLARY DATE: 1998/12/08 APPROVED BY: NISEN DATE: 1998/12/08 MATERIAL NO. SEE TABLE DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SCALE: 3.5:1 DESIGN UNITS: METRIC THIRD ANGLE PROJECTION	TITLE: SMA JACK R/A PCB TH 50 OHMS SMA-J/PCB MOLEX INCORPORATED DOCUMENT NO. SD-73391-008 SHEET NO. 1 OF 1
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			